



BASEBAND UNITS AND OPTICAL TRANSPORT

ENABLING FRONTHAUL TO BACKHAUL AND BEYOND

Our base station and optical transport connectivity solutions address the demands of the always-on edge of expanding wireless infrastructure. Along with increased capacity demands driven by the explosion of cloud and connected device growth, engineers need interconnects that enhance the design, implementation and maintenance of networks from the access point to the core. Our innovations in connectivity technologies

push the boundaries of speed and bandwidth within today's architectures and address challenging data rate, signal and power requirements of the emerging 5G mobile networks. TE Connectivity's (TE) solutions also include antenna expertise and high-speed board-to-board as well as cabled interconnects offering increased bandwidth for backplanes and midplanes.

FIND OUT MORE
te.com/BBU

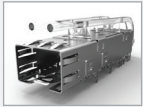


INPUT/OUTPUT (I/O)

I/O performance is the top priority for metro & core networks. Maximize your density & speed with TE's pluggable I/O connector and cages which support standard interfaces for data rates up to 100G.



5G RJ45 Connectors
Our jacks and plugs offer reliable and space saving solutions for flexible and time-saving installation, even in harsh environments.



5G SFP/SFP+ Connectors
SFP+ interconnect system supports data rates of 10 Gbps signal speeds and is backward compatible with SFP. Many cage configurations offered provide excellent shielding options.



5G QSFP/zQSFP+ Connectors
Our quad small form factor pluggable (QSFP) portfolio of interconnects offers a large range of simple and customizable design options.



RJ point five Connectors
This next-gen Ethernet link offers higher density solutions for a competitive total cost of ownership per port.

POWER

From bus bar to cable, hot-pluggability and blind mating—we offer robust power solutions for almost any design configuration.



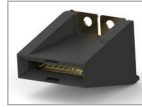
Open Compute Project (OCP) Power Connectors
The only solution fully compatible with the Open Rack V1 and V2 specifications.



5G ELCON Mini Connectors
These interconnects provide confidence in system performance with their low resistance, highly reliable interface.



RAPID LOCK Connectors
No install tools required for this fast, reliable replacement for power lugs.



CROWN CLIP Senior
Offers a low insertion/extraction force for high-current mating directly to a power bus bar.



CROWN CLIP Junior
Space efficient hot pluggable design for power supply and distribution applications.



Pluggable Bus Bar Cable Assemblies
Provides efficient and reliable power distribution and quick installation in a plug-and-play design.



Wave Crimp
Versatile solution designed for higher power needs. Able to bend through tight spaces; well suited to accommodate the shift from PCB to cable or bus bar.

INTERNAL INTERCONNECTS

TE's latest high-speed, high-density interconnects support a range of functions for the latest BBU and OT designs.



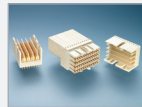
Fine Pitch Board-to-Board (BTB)
0.4 mm pitch plus new shielded board-to-FPC solution.



Free Height Connectors
These versatile connectors are useful for downsizing applications that require parallel stacked circuit boards.



M.2 NGFF Connectors
Save more than 20% of PCB real estate compared to the PCI Express Mini Card.



Z-PACK Slim UHD High-Speed Connectors
Designed to be among the densest connectors with the smallest possible footprint to free up valuable PCB space.



5G Board Level Shielding (BLS)
EMI shields that minimize crosstalk in tightly designed systems.



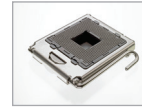
5G RF Connectors
A wide array of RF and standard coax connectors for any size base station.



Flexible Printed Circuit (FPC)
Space-saving, angled insertion connectors that can be placed in a wide range of PCB locations.

SOCKETS

A range of leading IC sockets and robust memory sockets allows designers to find the best products for their system.



5G Land Grid Array (LGA) Sockets
Socket technology for microprocessor packages up to 3647 positions.



5G DDR4 DIMM Connectors
Space savings, reduced height, improved power consumption, and higher data rates than the DDR3.

CABLE ASSEMBLIES

Supporting the latest standards and engineered for 25 Gbps and beyond. Custom solutions available.



5G Pluggable I/O Cable Assemblies
TE's high speed pluggable I/O copper cable assemblies are engineered for 25 Gbps and beyond.



5G FullAXS Mini Connectors
Next generation WiMAX and x-TTA connectivity designs require slim but rugged and easy-to-install cable assemblies for outdoor use.

SENSORS

State-of-the-art measurement solutions for increased control.



Humidity Sensors
Maintain optimal and efficient environments for people and equipment.



Temperature Sensors
Accurate temperature monitoring for energy efficiency.

